INTER-UNIVERSITY ACCELERATOR CENTRE

(An Autonomous Centre of UGC)
Aruna Asaf Ali Marg, New Delhi-110 067, INDIA

NOTICE INVITING E-TENDER

Tender No: IUAC/NIT/36/SKS/2019-20 **Dated: 27/08/2019**

Instructions for Online Bid Submission:

Inter-University Accelerator Centre (IUAC), invites online bids through e-Procurement Portal under two bid system, viz., Technical and Financial bids, from eligible and experienced parties for the work/supply of ""**Supply of Electronic & Electrical components** ".

Tender Documents may be downloaded from Central Public Procurement Portal **http://eprocure.gov.in/eprocure/app** and **www.iuac.res.in.**

Aspiring bidders who have not enrolled/registered in e-Procurement Portal should enroll/register before participating through the website **http://eprocure.gov.in/eprocure/app.**

Only bids received through e-procurement portal will be considered for opening. Bids not covering full scope of work/supply of the products/goods will be rejected and only complete bids will be considered.

Bids shall be submitted online only at CPPP website: **http://eprocure.gov.in/eprocure/app.** Tenderers/Contractors/Bidders are advised to follow the instructions provided in the e-procurement portal. Bid documents may be scanned with 100 dpi with black and white option which helps in reducing size of the scanned document.

IUAC reserves the right to accept / reject any/all tenders in part/full without assigning any reasons thereof.

Bidder has to select the payment option as **"offline"** to pay the **Tender Fee** and **Earnest Money Deposit (EMD)** as applicable. The Tender Fee and EMD shall be in the form of **Demand Draft** issued in favour of "**Inter-University Accelerator Centre, New Delhi**" and it should be deposited at IUAC before the bid opening. Bidders registered with MSME/NSIC are exempted from payments of EMD & tender fee. Copy of valid registration certificate should be uploaded in the portal.

Bidders are requested to note that they should necessarily submit their financial bids of all items in the format provided and no other format is acceptable. If the price bid has been given as a standard BOQ format with the tender document, then the same is to be downloaded and to be filled and submit it online without modifying the format. If the BOQ file is found to be modified by the bidder, the bid will be rejected.

For any clarification/amendment/corrigenda etc. to NIT before last date of submission of tender will only be available on website https://eprocure.gov.in and Bidders are requested to keep visiting this website for all updates and in case of any correspondence for clarifications needed, they may contact Administrative Officer (S&P) e-mail: joseph@iuac.res.in

E - TENDER DOCUMENT

Name of Work / Supply	**Supply of Electronic & Electrical components**
Tender Reference Number	IUAC/NIT/36/SKS/2019-20
Tender Value / Estimate	Rs. 11,00,000/-
Earnest Money Deposit	Rs. 22,000/- in the form of D.D.
Tender Document Fee	Rs. 590/-in the form of D.D.
Last Date and Time of Bid Submission	24/09/2019 at 3.00 p.m.
Date & Time for opening of Technical Bid **(Part-A)**	25/09/2019 at 3.30 p.m.
Date & time for opening of Price Bid **(Part -B)**	Will be intimated latter
Address for contact	Administrative Officer (S&P) Inter-university Accelerator Centre e-mail: joseph@iuac.res.in S. K. Suman e-mail: Phones: 011-24126018 & 24126022
Place of opening of the Tender	Committee Room, IUAC

Part-I: General Terms and Conditions of the Tender

1. **Submission of Tender:** Tenders should be uploaded on CPP Portal in two Parts i.e. Technical Bid (Part-A) and Price Bid (Part-B).

2. **Technical Bid (Part-A):** In this bid, the bidder shall upload scanned copies of following documents which are required for technical qualification. All documents uploaded by the bidder should be self-attested along with stamp). No deviations in respect of NIT conditions

are acceptable.

- **a)** Company particulars on letter head.
- **b)** Customers list of reputed institute/laboratories in India along with copy of previous orders where the bidder have supplied electronics components during last three years.
- **c)** The vendor should download the technical specifications compliance sheet (as given in Annexure - A) and should upload with duly signed & stamped by the bidder.
- **d)** Tender Acceptance Letter duly signed & stamped by the bidder.

Note: Technical bids which are not confirming to the technical specifications as per the Annexure-A will be disqualified.

3. **Price Bid / BOQ (Part-B):** In this bid, the bidder is required to quote his unconditional basic rates excluding taxes (GST) in the standard BOQ format provided. IUAC is exempted from Custom Duties and GST. Appropriate exemption certificates will be issued. Bidders are advised to quote all items in the BOQ. Incomplete quotes will be rejected. Price bid must be in **Indian rupees**. Bidder must include additional government duties/charges, Cartage charges etc (if any).

4. **Earnest Money Deposit (EMD)** : An earnest money of **Rs. 22000/-** (Rupees twenty two thousands only) has to be deposited at IUAC before the tender opening date and time. The EMD shall be only in the form of Bank Draft in favor of **Inter-University Accelerator Centre**, payable at **New Delhi**. No Cheque/Cash shall be accepted as EMD. The refund of EMD to all other bidders except the lowest bidder shall be made within 15 days from the date of opening of price bid. The refund of EMD of the successful bidder shall be made after the acceptance of material/items by IUAC.

   Exemption from EMD: Units registered with National Small Scale Industries Corporation (NSIC) are exempted from payment of EMD, subjected to:

   - **a)** The unit being registered with NSIC for the items tendered.
   - **b)** Self attested copy of valid NSIC registration Certificate is enclosed.
   - **c)** Photocopy of application for registration at NSIC or for renewal of NSIC will not be acceptable. Such offers will be treated as offers received without EMD.

5. **Validity of Tender:** Tender shall be valid for our acceptance without any change in rates and NIT conditions for a period of 90 days from the date of opening of the Technical bid. No escalation of cost will be acceptable in any condition after opening of tender.
6. **Escalation / Deviation**: No escalation or deviation shall be allowed till execution of order / contract.
7. **Payment Terms**: Payment will be released on complete delivery of goods at IUAC and its certification by the personnel concerned.
8. **Delivery Period:** 60 days from the date of placement of LOI/Purchase Order. Any delay in completing the supply for reasons attributable to the Contractor is liable for liquidated damages as per clause 10 of NIT.
9. **Correspondence:** All the correspondence in respect of tender / contractual obligation shall be made to "The Administrative Officer (S&P), Inter University Accelerator Centre, Aruna Asaf Ali Marg, New Delhi – 110067". E-mail: joseph@iuac.res.in, Phone: +91-11-24126018,

24126022.

10. **Liquidated damages:** In case the supply is delayed beyond the specified completion period for reasons attributable to the supplier, deductions on account of Liquidated Damages @ 1% of the supply value per week or part there of will be deducted subject to a maximum of 10% of the total cost.

11. **Tender Rejection:**

    IUAC reserves the right to accept/reject any/all tenders in part/full without assigning any reason whatsoever and the decision of the IUAC in this regard will be binding on all the bidders.
    a) Bids not covering full scope of work/supply of the products/goods may be summarily rejected. IUAC reserves the right to drop any item in the final order.
    b) If BOQ file is found to be modified by the bidder, the bid will be rejected.
    c) Tenders not complying with any of the provisions stated in this tender document are liable to be rejected.

12. IUAC reserves the right to reject or accept any or all the tenders in full or in part without assigning any reasons whatsoever, and the decision of the Centre in this regard will be binding on all the bidders. Director, IUAC reserves the right to accept or reject any tender without assigning any reason and does not bind himself to accept the lowest tender.

13. The contract shall be governed by the Indian Laws. Any dispute arising out of this contract will be subjected to jurisdiction of New Delhi / Delhi.

Accepted
(Signature of Bidder)

Annexure - A

Technical Specifications

Description of the item: Supply of Electronic & Electrical components as per the following specifications.

Sl.No	Description of items	Mfr Part Number	Manufacture	Qty	Unit
1	Capacitor polyester film 3.3uF,250V,10%, Radial Leaded	BFC237343335	Vishay	50	nos
2	Tantalum Capacitor,10uF,35V,±20%, Radial Leaded	MCCB1V106M2DCB	Multicomp	200	nos
3	Electrolytic Capacitor, Snap-in, 3300µF,35 V,± 20%,Radial Leaded	B41252A7338M000	Epcos	250	nos
4	Metal Foil Resistor, 500 ohm, 600 mW, ± 0.01%, Radial Leaded	Y0062500R000T9L	Vishay Foil Resistors	15	nos
5	Metal Foil Resistor, 1 Kohm, 600 mW, ± 0.01%, Radial Leaded	Y00071K00000T9L	Vishay Foil Resistors	10	nos
6	Metal Foil Resistor, 10 Kohm, 600 mW, ± 0.01%, Radial Leaded	Y078510K0000T9L	Vishay Foil Resistors	25	nos
7	Thick Film Current Sense Resistor, 0.1 ohm,100 W, ± 1%, SOT-227	TGHGCR1000FE	Ohmite	25	nos
8	Resistor network 10K, SIP-10Pin	4610X-101-103LF	Bourns	100	nos
9	Rotary Potentiometer, Wirewound, 20 kohm, 10 Turns, Linear, 2 W, ± 5%, 3590S Series	3590S-2-203L	Bourns	25	nos
10	Turns Counting Dial, 15 Turns, 6.35 mm, Satin Chrome, H Series	H-22-6A	Bourns	25	nos
11	Bridge Rectifier Diode, 6A, 800V, Through Hole	BR68	Rectron	150	nos
12	NPN BJT Transistor, 16A, 200 V, 60 hfe, TO-3	MJ15022G	On Semiconductor	300	nos
13	NPN BJT Transistor, -16A, -200 V, 60 hfe, TO-3	MJ15023G	On Semiconductor	25	nos
14	IC, TTL,Quad NAND Gate, DIP-14P	SN74LS00N	Texas Instruments	25	nos
15	IC,TTL, Inverters Hex Inverter, DIP-14P	SN74LS04N	Texas Instruments	25	nos
16	IC, TTL, Buffers & Line Drivers Hex, DIP-14P	SN74LS07N	Texas Instruments	75	nos
17	IC, TTL,Quad 2-input AND Gate ,DIP-14P	SN74LS08N	Texas Instruments	25	nos
18	IC, TTL, Hex Schmitt Trigger Inverter,DIP-14P	SN74LS14N	Texas Instruments	25	nos
19	IC, TTL, Dual D-Flip-Flops, DIP-14P	SN74LS74AN	Texas Instruments	100	nos

20	IC, TTL, Dual Monostable, DIP-16P	SN74LS123N	Texas Instruments	50	nos
21	IC, TTL, octal Buffer/Line Driver Inverting, DIP-20P	SN74HCT240N	Texas Instruments	50	nos
22	IC, TTL, 13-Input NAND Gates, DIP-16P	SN74ALS133N	Texas Instruments	25	nos
23	IC, TTL, Hex Buffers & Line Drivers,DIP-16P	74HCT367N	NXP	25	nos
24	IC, CMOS, Quad 2-Input NAND Schmitt Trigger,DIP-14P	CD4093BE	Texas Instruments	50	nos
25	IC, Bipolar Transistor Array, Darlington, NPN, DIP-16P	ULN2003A	ST Micro Electronics	75	nos
26	IC, Transistor Output Optocoupler, DIP-6P	4N35	Vishay	200	nos
27	IC, Transistor Output Optocoupler, DIP-16P	ILQ615-2	Vishay	150	nos
28	IC, Precision Operational Amplifier, DIP-8P	OP07CPZ	Analog Devices	50	nos
29	IC, Precision Operational Amplifiers Low Noise , DIP-8P	OP37GPZ	Analog Devices	25	nos
30	IC, JFET Operational Amplifiers, DIP-8P	TL072CP	Texas Instruments	200	nos
31	IC, Instrument Amplifier, DIP-8P	AD622ANZ	Analog Devices	25	nos
32	IC, Digital to Analogue Converter, 16 bit, DIP-28P	AD569KNZ	Analog Devices	20	nos
33	IC, Voltage Reference, Multiple Output, DIP-16P	AD588JQ	Analog Devices	20	nos
34	IC, Voltage Reference, Precision, DIP-8P	REF02CPZ	Analog Devices	25	nos
35	Dual 3-1/2 Digital LCD Panel Meter, 0mV to 200mV, ±1 %, 62 x 32 mm	DPM702S	Lascar	20	nos
36	Signal Relay, 24 Vdc, DPDT, 2 A, G5V-2 Series	G5V-2-24DC	Omron Electronic Components	50	nos
37	Rocker Switch, Illuminated, DPST, Off-On, Red, Panel, 16 A, 250 V	C1353VQ0/1RED	ARCOLECTRIC	25	nos
38	Red Square Push Button Lens for use with A3D Series	A3DA-500R	Omron Industrial Automation	60	nos
39	Pushbutton Momentary Switch, Standard, A3D Series, Square, Panel Mount	A3DA-7111	Omron Industrial Automation	60	nos
40	LED Lens, Red, 7.11 mm, Round with Flat Top, Polycarbonate	CLF280RTP	Multicomp	200	nos
41	Fuse PCB, 1A, 125V, Very Fast Acting, 2.8 x 7.1mm, Axial Leaded	0251001.MXL	Littlefuse	100	nos
42	Pin Receptacle, PCB, Solder, 1 Contacts, 0314 Series, Gold Plated Contacts	0314-0-15-15-34-27-10-0	Mill Max	600	nos

43	Heat Sink, TO-220/218, 8 mm, 50 mm, 100 mm	PPL1000B	ABL Heatsink	50	nos
44	Wire-To-Board Connector, Right Angle, Through Hole, Header, 2 Row, 26-Way, 2.54 mm, SEK 18 Series, Gold Plated	0918526 6903	Harting	50	nos
45	Wire-To-Board Connector, IDC / IDT, Receptacle, 2 Row, 26-Way, 2.54 mm, Gold Plated Contacts, SEK 18 series , Gold Plated	0918526 6803	Harting	50	nos
46	Wire-To-Board Connector, Right Angle, Through Hole, Header, 2 row, 50-Way, 2.54mm , SEK 18 Series, gold plated	0918550 6903	Harting	25	nos
47	Wire-To-Board Connector, Short Latch, Through Hole, Header, 2 row, 50-Way, 2.54mm, SEK 18 Series, gold plated	0918550 7914	Harting	25	nos
48	Wire-To-Board Connector, 2.54 mm, 2 row, 50 Contacts, Receptacle, SEK 18 Series, gold plated	0918550 6803	Harting	50	nos
49	DIN 41612 Connector, Type C Series, 64 Contacts, Plug, 2.54 mm, 2 Row, a + c	09 03 364 6921	Harting	125	nos
50	DIN 41612 Connector, Type C Series, 64 Contacts, Receptacle, 2.54 mm, 2 Row, a + c	09 03 264 6421	Harting	125	nos
51	Standard D Sub Connector, Plug, 50 Pin, Metal Body, Solder type	5502-50PA-01-F1	Multicomp	25	nos
52	D Sub Connector 9 Pin, Receptacle, Right Angle , PCB Solder type	SPC15383	Multicomp	50	nos
53	D Sub Backshell, DA, 45°, Zinc Body, MHD45ZK Series	MHD45ZK-15-K	MH Connectors	25	nos
54	PCB Mount Barrier Terminal Block, 9.53 mm, 1 Row, 4 Ways, 22 AWG, 12 AWG, 25 A	38720-7504	Molex	25	nos
55	Barrier Terminal Blocks , 4 Position, .375, Solder turret style	38720-3204	Molex	25	nos
56	Barrier Terminal Blocks , 8 Position, .375, Solder turret style	38720-3208	Molex	50	nos

Name & Signature of Tenderer
Company with Seal

Annexure - B

BOQ / PRICE BID

(Price should be quoted in the standard BOQ format of this tender)

Tender Inviting Authority: INTER UNIVERSITY ACCELERATOR CENTRE

Name of Work/Supply : Supply of Electronic & Electrical components as per the Annexure-A.

Sl.No	Description of items	Qty	Unit
1	Capacitor polyester film 3.3uF,250V,10%, Radial Leaded (Mfr: Vishay; Part No: BFC237343335)	50	nos
2	Tantalum Capacitor,10uF,35V,±20%, Radial Leaded (Mfr: Multicomp; Part No: MCCB1V106M2DCB)	200	nos
3	Electrolytic Capacitor, Snap-in, 3300µF,35 V,± 20%,Radial Leaded (Mfr: Epcos; Part No: B41252A7338M000)	250	nos
4	Metal Foil Resistor, 500 ohm, 600 mW, ± 0.01%, Radial Leaded (Mfr: Vishay Foil Resistors; Part No: Y0062500R000T9L)	15	nos
5	Metal Foil Resistor, 1 Kohm, 600 mW, ± 0.01%, Radial Leaded (Mfr: Vishay Foil Resistors; Part No: Y00071K00000T9L)	10	nos
6	Metal Foil Resistor, 10 Kohm, 600 mW, ± 0.01%, Radial Leaded (Mfr: Vishay Foil Resistors; Part No: Y078510K0000T9L)	25	nos
7	Thick Film Current Sense Resistor, 0.1 ohm,100 W, ± 1%, SOT-227 (Mfr: Ohmite; Part No: TGHGCR1000FE)	25	nos
8	Resistor network 10K, SIP-10Pin (Mfr: Bourns; Part No: 4610X-101-103LF)	100	nos
9	Rotary Potentiometer, Wirewound, 20 kohm, 10 Turns, Linear, 2 W, ± 5%, 3590S Series (Mfr: Bourns; Part No: 3590S-2-203L)	25	nos
10	Turns Counting Dial, 15 Turns, 6.35 mm, Satin Chrome, H Series (Mfr: Bourns; Part No: H-22-6A)	25	nos
11	Bridge Rectifier Diode, 6A, 800V, Through Hole (Mfr: Rectron ; Part No: BR68)	150	nos
12	NPN BJT Transistor, 16A, 200 V, 60 hfe, TO-3 (Mfr: On Semiconductor; Part No: MJ15022G)	300	nos
13	NPN BJT Transistor, -16A, -200 V, 60 hfe, TO-3 (Mfr: On Semiconductor; Part No: MJ15023G)	25	nos
14	IC, TTL,Quad NAND Gate, DIP-14P (Mfr: Texas Instruments; Part No: SN74LS00N)	25	nos
15	IC,TTL, Inverters Hex Inverter, DIP-14P (Mfr: Texas Instruments; Part No: SN74LS04N)	25	nos
16	IC, TTL, Buffers & Line Drivers Hex, DIP-14P (Mfr: Texas Instruments; Part No: SN74LS07N)	75	nos
17	IC, TTL,Quad 2-input AND Gate ,DIP-14P (Mfr: Texas Instruments; Part No: SN74LS08N)	25	nos

18	IC, TTL, Hex Schmitt Trigger Inverter,DIP-14P (Mfr: Texas Instruments; Part No: SN74LS14N)	25	nos
19	IC, TTL, Dual D-Flip-Flops, DIP-14P (Mfr: Texas Instruments; Part No: SN74LS74AN)	100	nos
20	IC, TTL, Dual Monostable, DIP-16P (Mfr: Texas Instruments; Part No: SN74LS123N)	50	nos
21	IC, TTL, octal Buffer/Line Driver Inverting, DIP-20P (Mfr: Texas Instruments; Part No: SN74HCT240N)	50	nos
22	IC, TTL, 13-Input NAND Gates, DIP-16P (Mfr: Texas Instruments; Part No: SN74ALS133N)	25	nos
23	IC, TTL, Hex Buffers & Line Drivers,DIP-16P (Mfr: NXP; Part No: 74HCT367N)	25	nos
24	IC, CMOS, Quad 2-Input NAND Schmitt Trigger,DIP-14P (Mfr: Texas Instruments; Part No: CD4093BE)	50	nos
25	IC, Bipolar Transistor Array, Darlington, NPN, DIP-16P (Mfr: ST Micro Electronics; Part No: ULN2003A)	75	nos
26	IC, Transistor Output Optocoupler, DIP-6P (Mfr: Vishay; Part No: 4N35)	200	nos
27	IC, Transistor Output Optocoupler, DIP-16P (Mfr: Vishay; Part No: ILQ615-2)	150	nos
28	IC, Precision Operational Amplifier, DIP-8P (Mfr: Analog Devices; Part No: OP07CPZ)	50	nos
29	IC, Precision Operational Amplifiers Low Noise , DIP-8P (Mfr: Analog Devices; Part No: OP37GPZ)	25	nos
30	IC, JFET Operational Amplifiers, DIP-8P (Mfr: Texas Instruments; Part No: TL072CP)	200	nos
31	IC, Instrument Amplifier, DIP-8P (Mfr: Analog Devices; Part No: AD622ANZ)	25	nos
32	IC, Digital to Analogue Converter, 16 bit, DIP-28P (Mfr: Analog Devices; Part No: AD569KNZ)	20	nos
33	IC, Voltage Reference, Multiple Output, DIP-16P (Mfr: Analog Devices; Part No: AD588JQ)	20	nos
34	IC, Voltage Reference, Precision, DIP-8P (Mfr: Analog Devices; Part No: REF02CPZ)	25	nos
35	Dual 3-1/2 Digital LCD Panel Meter, 0mV to 200mV, ±1 %, 62 x 32 mm (Mfr: Lascar; Part No: DPM702S)	20	nos
36	Signal Relay, 24 Vdc, DPDT, 2 A, G5V-2 Series (Mfr: Omron Electronic Components; Part No: G5V-2-24DC)	50	nos
37	Rocker Switch, Illuminated, DPST, Off-On, Red, Panel, 16 A, 250 V (Mfr: ARCOLECTRIC; Part No: C1353VQ0/1RED)	25	nos
38	Red Square Push Button Lens for use with A3D Series (Mfr: Omron Industrial Automation; Part No: A3DA-500R)	60	nos
39	Pushbutton Momentary Switch, Standard, A3D Series, Square, Panel Mount (Mfr: Omron Industrial Automation; Part No: A3DA-7111)	60	nos
40	LED Lens, Red, 7.11 mm, Round with Flat Top, Polycarbonate (Mfr: Multicomp; Part No: CLF280RTP)	200	nos

41	Fuse PCB, 1A, 125V, Very Fast Acting, 2.8 x 7.1mm, Axial Leaded (Mfr: Littlefuse; Part No: 0251001.MXL)	100	nos
42	Pin Receptacle, PCB, Solder, 1 Contacts, 0314 Series, Gold Plated Contacts (Mfr: Mill Max; Part No: 0314-0-15-15-34-27-10-0)	600	nos
43	Heat Sink, TO-220/218, 8 mm, 50 mm, 100 mm (Mfr: ABL Heatsink; Part No: PPL1000B)	50	nos
44	Wire-To-Board Connector, Right Angle, Through Hole, Header, 2 Row, 26-Way, 2.54 mm, SEK 18 Series, Gold Plated (Mfr: Harting; Part No: 0918526 6903)	50	nos
45	Wire-To-Board Connector, IDC / IDT, Receptacle, 2 Row, 26-Way, 2.54 mm, Gold Plated Contacts, SEK 18 series , Gold Plated (Mfr: Harting; Part No: 0918526 6803)	50	nos
46	Wire-To-Board Connector, Right Angle, Through Hole, Header, 2 row, 50-Way, 2.54mm , SEK 18 Series, gold plated (Mfr: Harting; Part No: 0918550 6903)	25	nos
47	Wire-To-Board Connector, Short Latch, Through Hole, Header, 2 row, 50-Way, 2.54mm, SEK 18 Series, gold plated (Mfr: Harting; Part No: 0918550 7914)	25	nos
48	Wire-To-Board Connector, 2.54 mm, 2 row, 50 Contacts, Receptacle, SEK 18 Series, gold plated (Mfr: Harting; Part No: 0918550 6803)	50	nos
49	DIN 41612 Connector, Type C Series, 64 Contacts, Plug, 2.54 mm, 2 Row, a + c (Mfr: Harting; Part No: 09 03 364 6921)	125	nos
50	DIN 41612 Connector, Type C Series, 64 Contacts, Receptacle, 2.54 mm, 2 Row, a + c (Mfr: Harting; Part No: 09 03 264 6421)	125	nos
51	Standard D Sub Connector, Plug, 50 Pin, Metal Body, Solder type (Mfr: Multicomp; Part No: 5502-50PA-01-F1)	25	nos
52	D Sub Connector 9 Pin, Receptacle, Right Angle , PCB Solder type (Mfr: Multicomp; Part No: SPC15383)	50	nos
53	D Sub Backshell, DA, 45°, Zinc Body, MHD45ZK Series (Mfr: MH Connectors; Part No: MHD45ZK-15-K)	25	nos
54	PCB Mount Barrier Terminal Block, 9.53 mm, 1 Row, 4 Ways, 22 AWG, 12 AWG, 25 A (Mfr: Molex; Part No: 38720-7504)	25	nos
55	Barrier Terminal Blocks , 4 Position, .375, Solder turret style (Mfr: Molex; Part No: 38720-3204)	25	nos
56	Barrier Terminal Blocks , 8 Position, .375, Solder turret style (Mfr: Molex; Part No: 38720-3208)	50	nos

Name & Signature of Tenderer Company with Seal

TENDER ACCEPTANCE LETTER

(To be given on Company Letter Head)

Date: ____________________

To
The Administrative Officer (S&P)
Inter-University Accelerator Centre
Aruna Asaf Ali Marg
New Delhi-110 067.

Sub: Acceptance of Terms & Conditions of Tender.

Tender Reference No: ____

Name of Tender / Work :____

Dear Sir,

1. We have downloaded / obtained the tender document(s) for the above mentioned 'Tender/Work' from the web site(s) namely: ____ ____ as per your advertisement, given in the above mentioned website(s).

2. We hereby certify that we have read the entire terms and conditions of the tender documents from Page No. _______ to ___ ___ (including all documents like annexure(s), schedule(s), etc .,), which form part of the contract agreement and we shall abide hereby by the terms / conditions / clauses contained therein.

3. The corrigendum(s) issued from time to time by your department/ organisation too have also been taken into consideration, while submitting this acceptance letter.

4. We hereby unconditionally accept the tender conditions of above mentioned tender document(s) / corrigendum(s) in its totality / entirety.

5. We do hereby declare that our Firm has not been blacklisted/ debarred by any Govt. Department/ Public sector undertaking.

6. We certify that all information furnished by the our Firm is true & correct and in the event that the information is found to be incorrect/untrue or found violated, then your department/ organisation shall without giving any notice or reason therefore or summarily reject the bid or terminate the contract, without prejudice to any other rights or remedy including the forfeiture of the full said earnest money deposit absolutely.

Yours Faithfully,

(Signature of the Bidder, with Official Seal)